

Applications

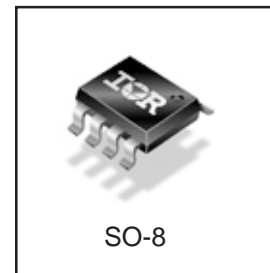
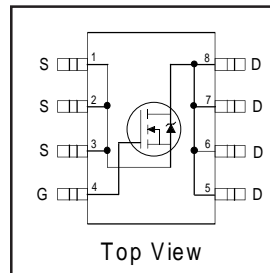
- High Frequency Isolated DC-DC Converters with Synchronous Rectification for Telecom and Industrial Use
- High Frequency Buck Converters for Computer Processor Power

HEXFET® Power MOSFET

| | | |
|------------------------|-------------------------------|----------------------|
| V_{DSS} | R_{DS(on)} max | I_D |
| 30V | 8.0mΩ | 14A |

Benefits

- Ultra-Low Gate Impedance
- Very Low R_{DS(on)}
- Fully Characterized Avalanche Voltage and Current



Absolute Maximum Ratings

| Symbol | Parameter | Max. | Units |
|--|---|--------------|-------|
| V _{DS} | Drain-Source Voltage | 30 | V |
| V _{GS} | Gate-to-Source Voltage | ± 30 | V |
| I _D @ T _A = 25°C | Continuous Drain Current, V _{GS} @ 10V | 14 | A |
| I _D @ T _A = 70°C | Continuous Drain Current, V _{GS} @ 10V | 11 | |
| I _{DM} | Pulsed Drain Current ^① | 110 | |
| P _D @ T _A = 25°C | Maximum Power Dissipation ^③ | 2.5 | W |
| P _D @ T _A = 70°C | Maximum Power Dissipation ^③ | 1.6 | W |
| | Linear Derating Factor | 0.02 | mW/°C |
| T _J , T _{STG} | Junction and Storage Temperature Range | -55 to + 150 | °C |

Thermal Resistance

| Symbol | Parameter | Typ. | Max. | Units |
|------------------|----------------------------------|------|------|-------|
| R _{θJL} | Junction-to-Drain Lead | — | 20 | °C/W |
| R _{θJA} | Junction-to-Ambient ^④ | — | 50 | |

Notes ① through ④ are on page 8
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Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|---------------------------------|--------------------------------------|------|-------|------|---------------------|--|
| $V_{(BR)DSS}$ | Drain-to-Source Breakdown Voltage | 30 | — | — | V | $V_{GS} = 0V, I_D = 250\mu A$ |
| $\Delta V_{(BR)DSS}/\Delta T_J$ | Breakdown Voltage Temp. Coefficient | — | 0.029 | — | V/ $^\circ\text{C}$ | Reference to $25^\circ\text{C}, I_D = 1mA$ |
| $R_{DS(on)}$ | Static Drain-to-Source On-Resistance | — | 6.3 | 8.0 | $m\Omega$ | $V_{GS} = 16V, I_D = 14A$ ③ |
| | | — | 7.0 | 9.0 | | $V_{GS} = 10V, I_D = 11A$ ③ |
| $V_{GS(th)}$ | Gate Threshold Voltage | 2.0 | — | 4.0 | V | $V_{DS} = V_{GS}, I_D = 250\mu A$ |
| I_{DSS} | Drain-to-Source Leakage Current | — | — | 20 | μA | $V_{DS} = 24V, V_{GS} = 0V$ |
| | | — | — | 100 | | $V_{DS} = 24V, V_{GS} = 0V, T_J = 125^\circ\text{C}$ |
| I_{GSS} | Gate-to-Source Forward Leakage | — | — | 200 | nA | $V_{GS} = 24V$ |
| | Gate-to-Source Reverse Leakage | — | — | -200 | | $V_{GS} = -24V$ |

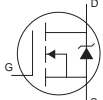
Dynamic @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

| Symbol | Parameter | Min. | Typ. | Max. | Units | Conditions |
|--------------|---------------------------------|------|------|------|-------|-----------------------------|
| g_{fs} | Forward Transconductance | 26 | — | — | S | $V_{DS} = 15V, I_D = 11A$ |
| Q_g | Total Gate Charge | — | 39 | 59 | nC | $I_D = 11A$ |
| Q_{gs} | Gate-to-Source Charge | — | 11 | 17 | | $V_{DS} = 15V$ |
| Q_{gd} | Gate-to-Drain ("Miller") Charge | — | 8.7 | 13 | | $V_{GS} = 10V$ ③ |
| Q_{oss} | Output Gate Charge | — | 29 | 44 | | $V_{GS} = 0V, V_{DS} = 16V$ |
| $t_{d(on)}$ | Turn-On Delay Time | — | 10 | — | ns | $V_{DD} = 15V$ |
| t_r | Rise Time | — | 4.6 | — | | $I_D = 11A$ |
| $t_{d(off)}$ | Turn-Off Delay Time | — | 22 | — | | $R_G = 1.8\Omega$ |
| t_f | Fall Time | — | 5.0 | — | | $V_{GS} = 10V$ ③ |
| C_{iss} | Input Capacitance | — | 2410 | — | pF | $V_{GS} = 0V$ |
| C_{oss} | Output Capacitance | — | 1100 | — | | $V_{DS} = 15V$ |
| C_{rss} | Reverse Transfer Capacitance | — | 110 | — | | $f = 1.0MHz$ |

Avalanche Characteristics

| Symbol | Parameter | Typ. | Max. | Units |
|----------|--------------------------------|------|------|-------|
| E_{AS} | Single Pulse Avalanche Energy② | — | 280 | mJ |
| I_{AR} | Avalanche Current① | — | 11 | A |

Diode Characteristics

| Symbol | Parameter | Min. | Typ. | Max. | Units | Conditions |
|----------|--|------|------|------|-------|--|
| I_S | Continuous Source Current (Body Diode) | — | — | 2.3 | A | MOSFET symbol showing the integral reverse p-n junction diode.  |
| I_{SM} | Pulsed Source Current (Body Diode) ① | — | — | 110 | | |
| V_{SD} | Diode Forward Voltage | — | 0.82 | 1.3 | V | $T_J = 25^\circ\text{C}, I_S = 11A, V_{GS} = 0V$ ③ |
| | | — | 0.68 | — | | $T_J = 125^\circ\text{C}, I_S = 11A, V_{GS} = 0V$ |
| t_{rr} | Reverse Recovery Time | — | 51 | 77 | ns | $T_J = 25^\circ\text{C}, I_F = 11A, V_R = 20V$ |
| Q_{rr} | Reverse Recovery Charge | — | 87 | 130 | nC | $di/dt = 100A/\mu s$ ③ |
| t_{rr} | Reverse Recovery Time | — | 52 | 78 | ns | $T_J = 125^\circ\text{C}, I_F = 11A, V_R = 20V$ |
| Q_{rr} | Reverse Recovery Charge | — | 93 | 140 | nC | $di/dt = 100A/\mu s$ ③ |

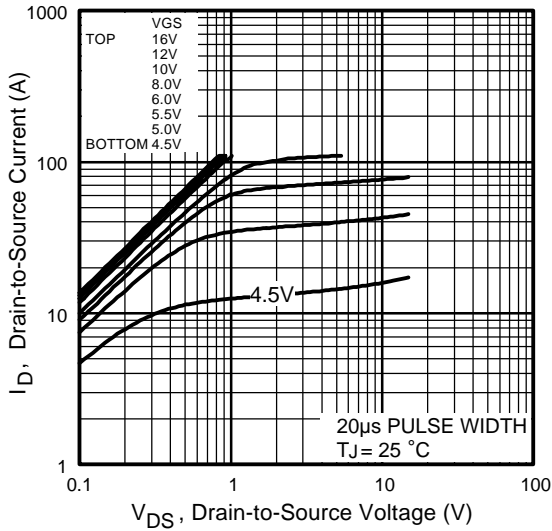


Fig 1. Typical Output Characteristics

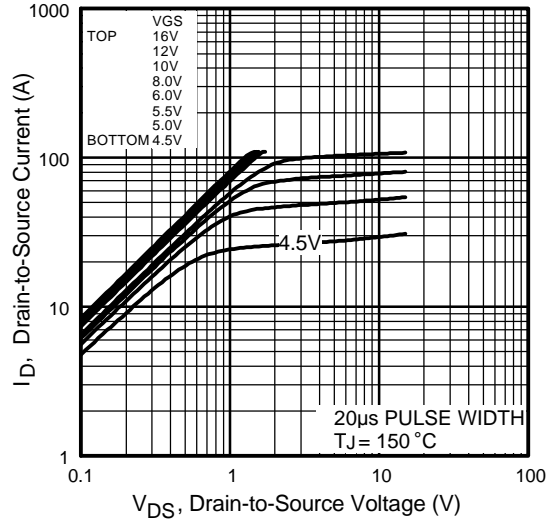


Fig 2. Typical Output Characteristics

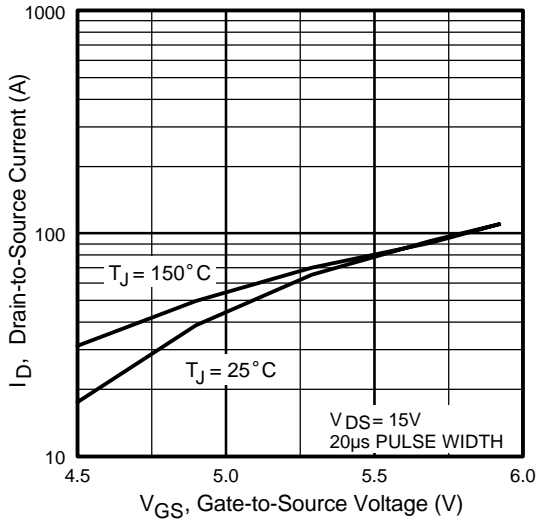


Fig 3. Typical Transfer Characteristics

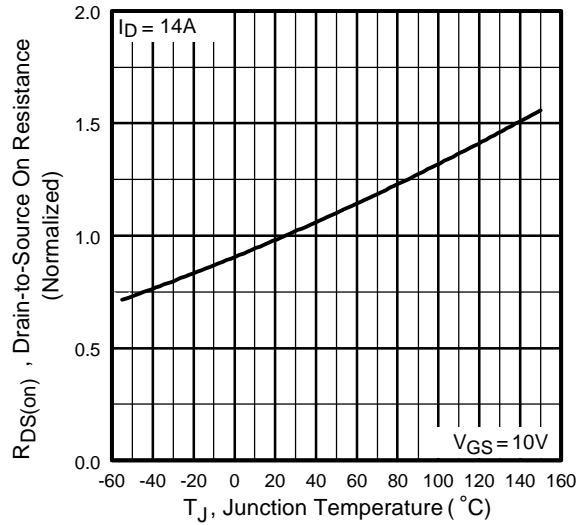


Fig 4. Normalized On-Resistance Vs. Temperature

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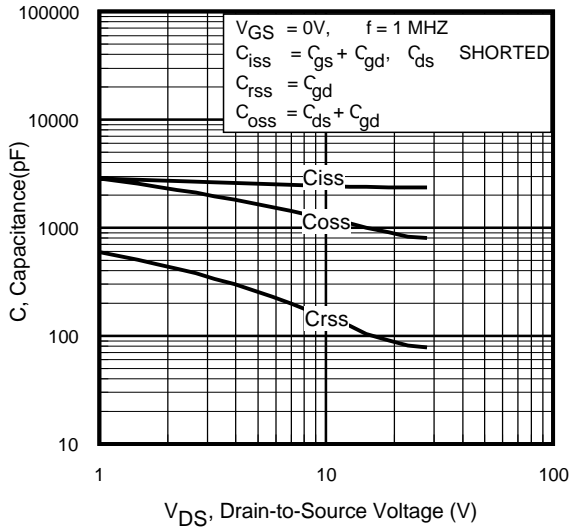


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

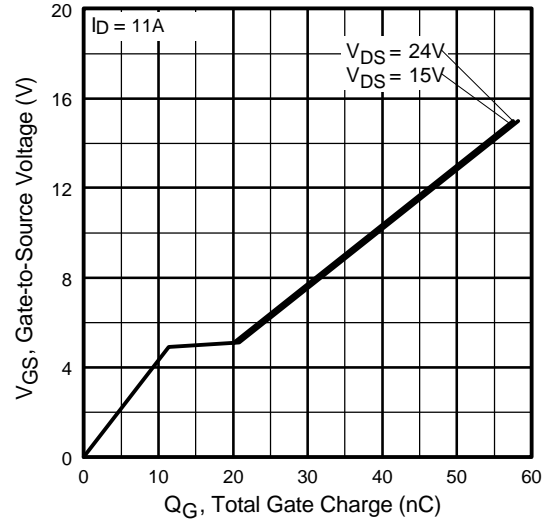


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

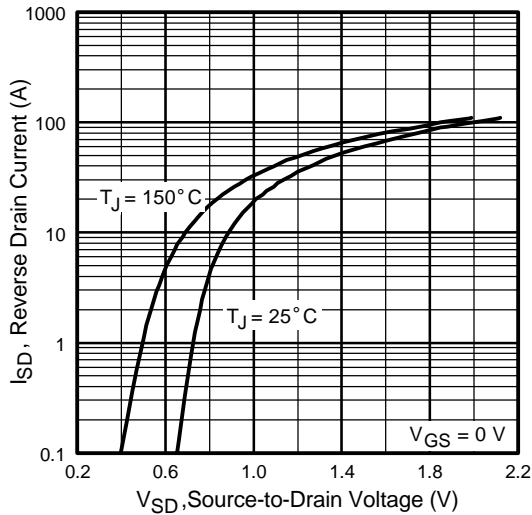


Fig 7. Typical Source-Drain Diode Forward Voltage

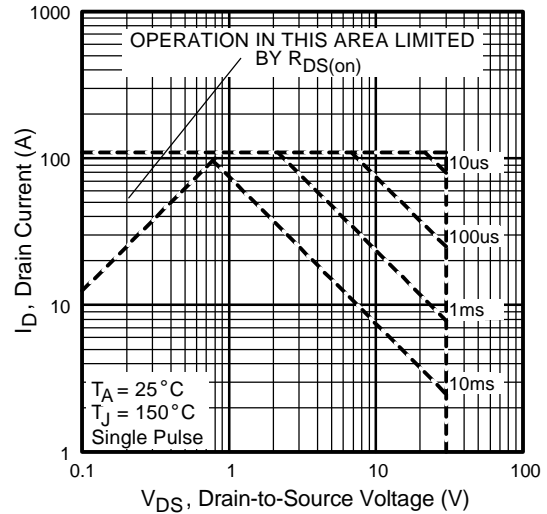


Fig 8. Maximum Safe Operating Area

Fig 6. On-Resistance Vs. Drain Current

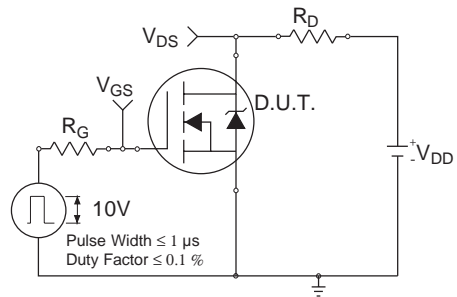
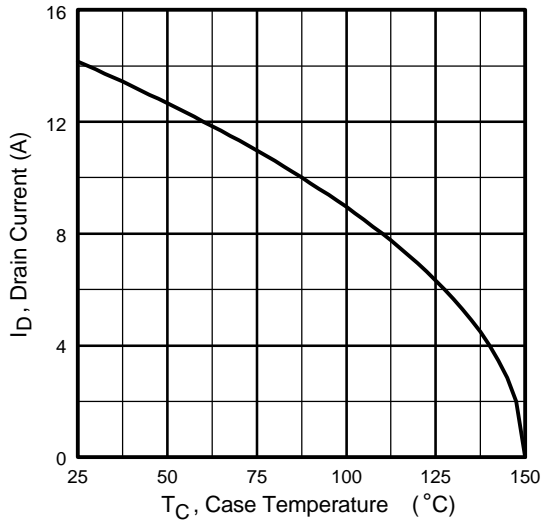


Fig 10a. Switching Time Test Circuit

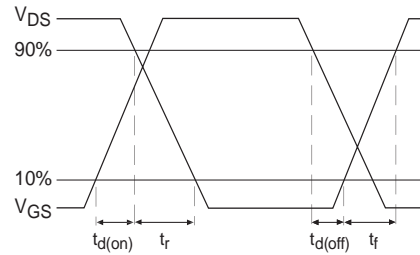


Fig 10b. Switching Time Waveforms

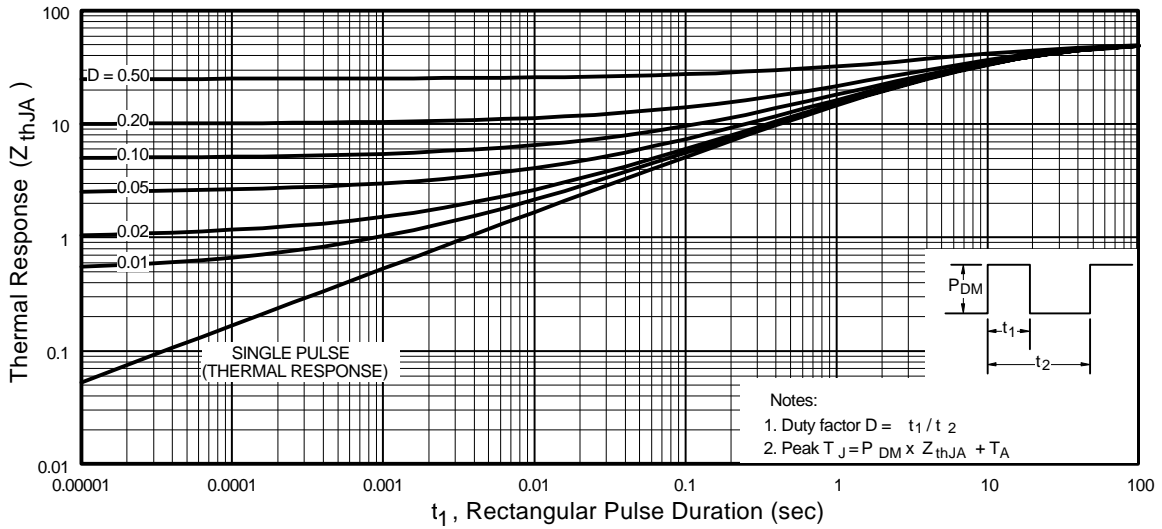


Fig 10. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

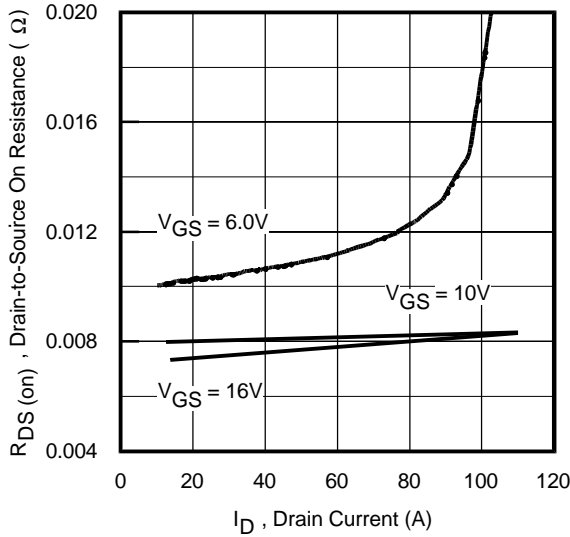


Fig 12. On-Resistance Vs. Drain Current

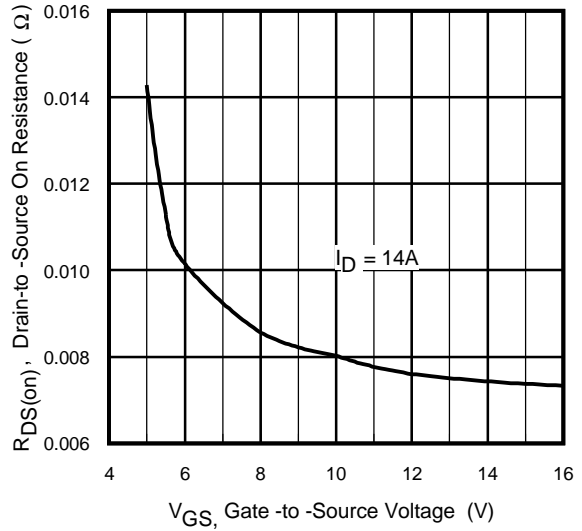


Fig 13. On-Resistance Vs. Gate Voltage

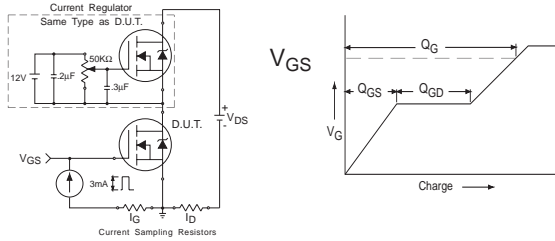


Fig 13a&b. Basic Gate Charge Test Circuit and Waveform

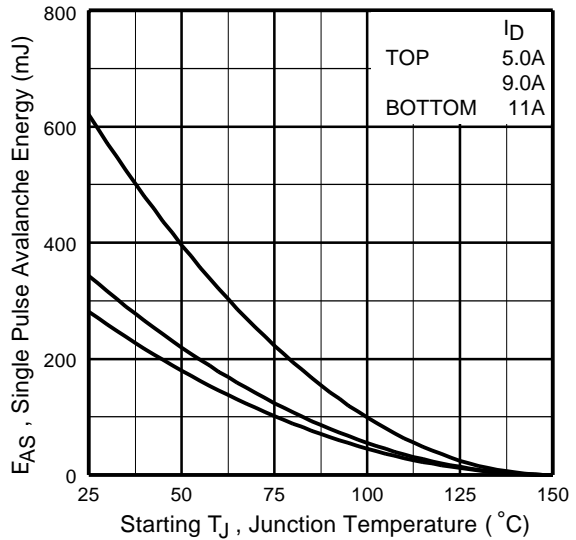


Fig 14c. Maximum Avalanche Energy Vs. Drain Current

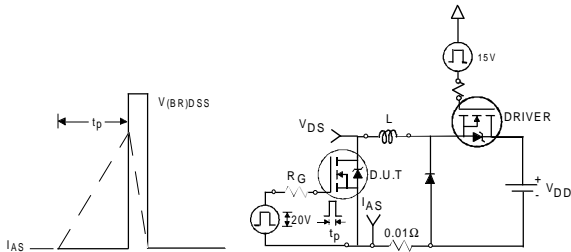
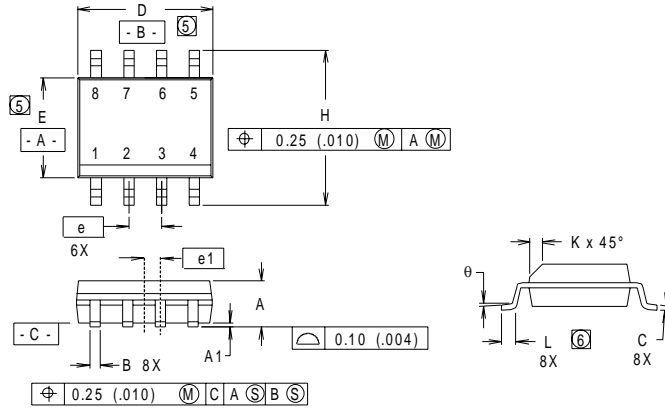


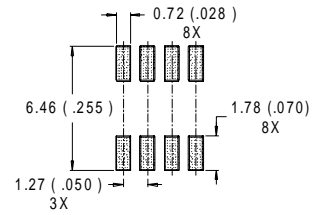
Fig 14a&b. Unclamped Inductive Test circuit and Waveforms

SO-8 Package Details



| DIM | INCHES | | MILLIMETERS | |
|-----|------------|-------|-------------|------|
| | MIN | MAX | MIN | MAX |
| A | .0532 | .0688 | 1.35 | 1.75 |
| A1 | .0040 | .0098 | 0.10 | 0.25 |
| B | .014 | .018 | 0.36 | 0.46 |
| C | .0075 | .0098 | 0.19 | 0.25 |
| D | .189 | .196 | 4.80 | 4.98 |
| E | .150 | .157 | 3.81 | 3.99 |
| e | .050 BASIC | | 1.27 BASIC | |
| e1 | .025 BASIC | | 0.635 BASIC | |
| H | .2284 | .2440 | 5.80 | 6.20 |
| K | .011 | .019 | 0.28 | 0.48 |
| L | 0.16 | .050 | 0.41 | 1.27 |
| θ | 0° | 8° | 0° | 8° |

RECOMMENDED FOOTPRINT

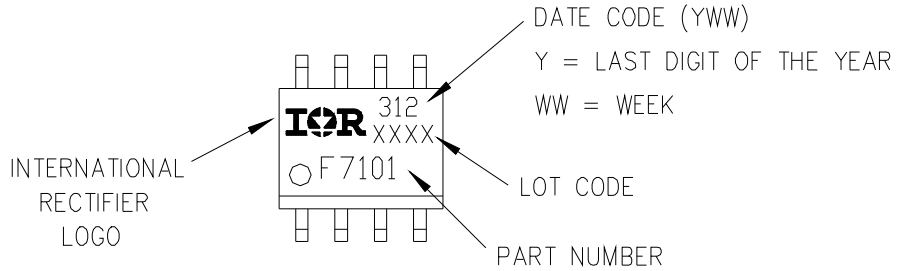


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION : INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS
MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.006).
6. DIMENSIONS IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE..

SO-8 Part Marking

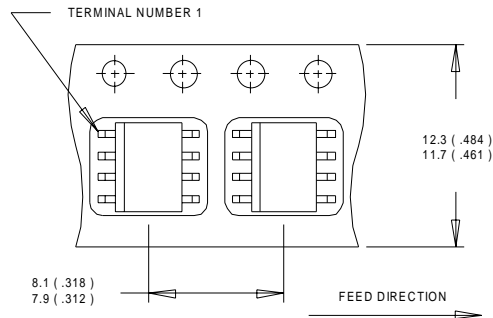
EXAMPLE: THIS IS AN IRF7101



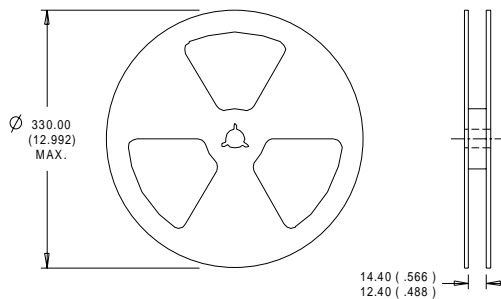
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SO-8 Tape and Reel



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
 2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting $T_J = 25^\circ\text{C}$, $L = 4.6\text{mH}$
 $R_G = 25\Omega$, $I_{AS} = 11\text{A}$.
- ③ Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.
- ④ When mounted on 1 inch square copper board, $t < 10\text{ sec}$

Data and specifications subject to change without notice.
This product has been designed and qualified for the Industrial market.
Qualification Standards can be found on IR's Web site.

International
IR Rectifier

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